

ABSTRACT

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APPARATUS AND METHOD OF PLACING  
SOLDER BALLS ONTO A SUBSTRATE

10 The invention provides an apparatus and method for positioning solder balls  
in a desired array on a substrate. A positioning means is provided for  
positioning the solder balls in positions corresponding to the array of positions  
the solder balls are to take up on the substrate. A container for receiving a  
plurality of solder balls and which is movable between a first position remote  
from the positioning means and a second position directly thereover supplies  
15 solder balls to the positioning means. Means are provided to bias the solder  
balls in the direction of movement of the container from the first to the second  
position whereby to reduce or obviate damage to the solder balls during such  
movement.

(Fig 2a)

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